

# SEMiX302GB126HDs



SEMiX® 2s

## Trench IGBT Modules

### SEMiX302GB126HDs

#### Features

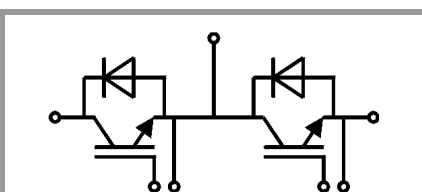
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

#### Typical Applications\*

- AC inverter drives
- UPS
- Electronic Welding

#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.
- Not for new design



GB

Absolute Maximum Ratings				
Symbol	Conditions	Values	Unit	
<b>IGBT</b>				
$V_{CES}$		1200	V	
$I_C$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	311	A
		$T_c = 80^\circ\text{C}$	218	A
$I_{Cnom}$		200	A	
$I_{CRM}$	$I_{CRM} = 2 \times I_{Cnom}$	400	A	
$V_{GES}$		-20 ... 20	V	
$t_{psc}$	$V_{CC} = 600\text{ V}$ $V_{GE} \leq 20\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 125^\circ\text{C}$	10	$\mu\text{s}$
$T_j$		-40 ... 150	$^\circ\text{C}$	
<b>Inverse diode</b>				
$I_F$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	292	A
		$T_c = 80^\circ\text{C}$	202	A
$I_{Fnom}$		200	A	
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$	400	A	
$I_{FSM}$	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	1300	A	
$T_j$		-40 ... 150	$^\circ\text{C}$	
<b>Module</b>				
$I_{t(RMS)}$		600	A	
$T_{stg}$		-40 ... 125	$^\circ\text{C}$	
$V_{isol}$	AC sinus 50Hz, $t = 1\text{ min}$	4000	V	

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
<b>IGBT</b>					
$V_{CE(sat)}$	$I_C = 200\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.7	2.1	V
		$T_j = 125^\circ\text{C}$	2	2.45	V
$V_{CE0}$		$T_j = 25^\circ\text{C}$	1	1.2	V
		$T_j = 125^\circ\text{C}$	0.9	1.1	V
$r_{CE}$	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	3.5	4.5	$\text{m}\Omega$
		$T_j = 125^\circ\text{C}$	5.5	6.8	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 8\text{ mA}$	5	5.8	6.5	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	$\text{mA}$
		$T_j = 125^\circ\text{C}$			$\text{mA}$
$C_{ies}$	$V_{CE} = 25\text{ V}$		14.4		nF
$C_{oes}$	$V_{GE} = 0\text{ V}$		0.75		nF
$C_{res}$			0.65		nF
$Q_G$	$V_{GE} = -8\text{ V...}+15\text{ V}$		1600		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		3.75		$\Omega$
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 125^\circ\text{C}$	320		ns
$t_r$	$I_C = 200\text{ A}$	$T_j = 125^\circ\text{C}$	50		ns
		$T_j = 125^\circ\text{C}$			
$E_{on}$	$R_{G on} = 2.8\ \Omega$	$T_j = 125^\circ\text{C}$	30		mJ
$t_{d(off)}$	$R_{G off} = 2.8\ \Omega$	$T_j = 125^\circ\text{C}$	600		ns
$t_f$		$T_j = 125^\circ\text{C}$	100		ns
$E_{off}$		$T_j = 125^\circ\text{C}$	26		mJ
$R_{th(j-c)}$	per IGBT			0.12	K/W



SEMiX<sup>®</sup> 2s

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- High short circuit capability
- UL recognised file no. E63532

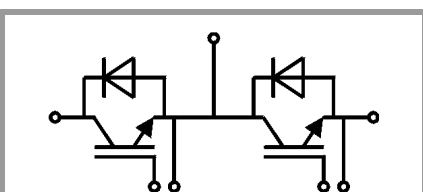
#### Typical Applications\*

- AC inverter drives
- UPS
- Electronic Welding

#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.
- Not for new design

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse diode</b>						
$V_F = V_{EC}$	$I_F = 200\text{ A}$ $V_{GE} = 0\text{ V}$ chip	$T_j = 25^\circ\text{C}$		1.6	1.80	V
		$T_j = 125^\circ\text{C}$		1.6	1.8	V
$V_{F0}$		$T_j = 25^\circ\text{C}$	0.9	1	1.1	V
		$T_j = 125^\circ\text{C}$	0.7	0.8	0.9	V
$r_F$		$T_j = 25^\circ\text{C}$	2.5	3.0	3.5	m $\Omega$
		$T_j = 125^\circ\text{C}$	3.5	4.0	4.5	m $\Omega$
$I_{RRM}$	$I_F = 200\text{ A}$	$T_j = 125^\circ\text{C}$		290		A
$Q_{rr}$	$di/dt_{off} = 5900\text{ A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		55		$\mu\text{C}$
$E_{rr}$	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 125^\circ\text{C}$		22.5		mJ
$R_{th(j-c)}$	per diode				0.19	K/W
<b>Module</b>						
$L_{CE}$				18		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m $\Omega$
		$T_C = 125^\circ\text{C}$		1		m $\Omega$
$R_{th(c-s)}$	per module			0.045		K/W
$M_s$	to heat sink (M5)		3		5	Nm
$M_t$		to terminals (M6)	2.5		5	Nm
						Nm
$w$					250	g
<b>Temperatur Sensor</b>						
$R_{100}$	$T_C=100^\circ\text{C}$ ( $R_{25}=5\text{ k}\Omega$ )			$493 \pm 5\%$		$\Omega$
$B_{100/125}$	$R_{(T)}=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$ ; $T[\text{K}]$ ;			$3550$ $\pm 2\%$		K



GB

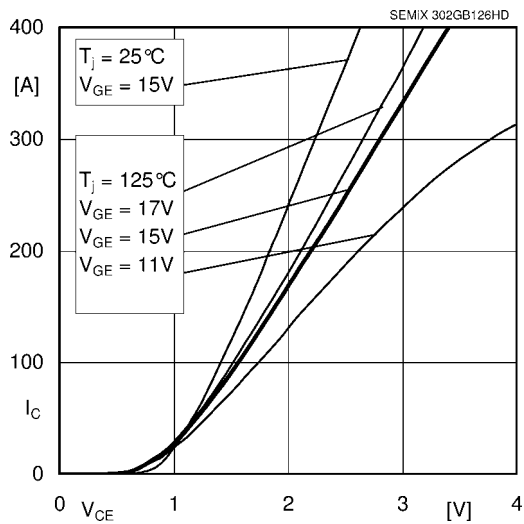


Fig. 1: Typ. output characteristic, inclusive  $R_{CC'+EE'}$

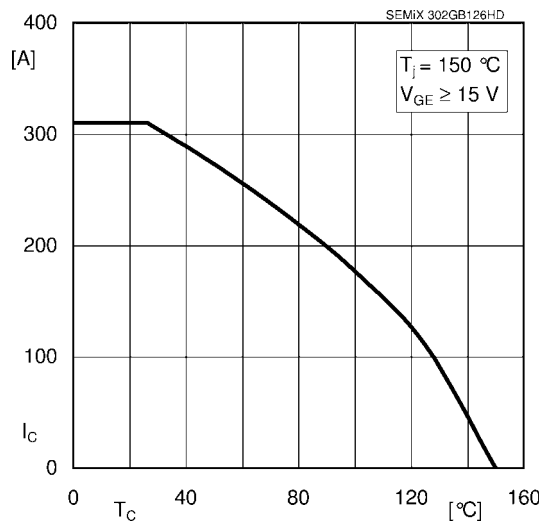


Fig. 2: Rated current vs. temperature  $I_C = f(T_C)$

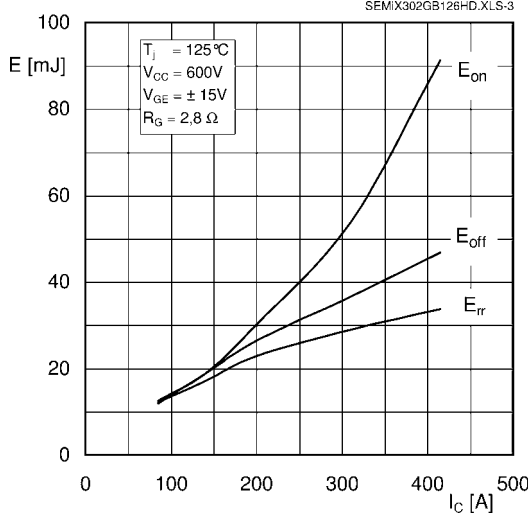


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

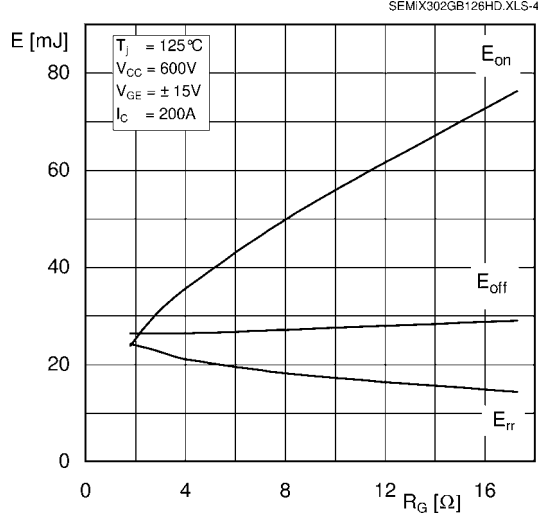


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

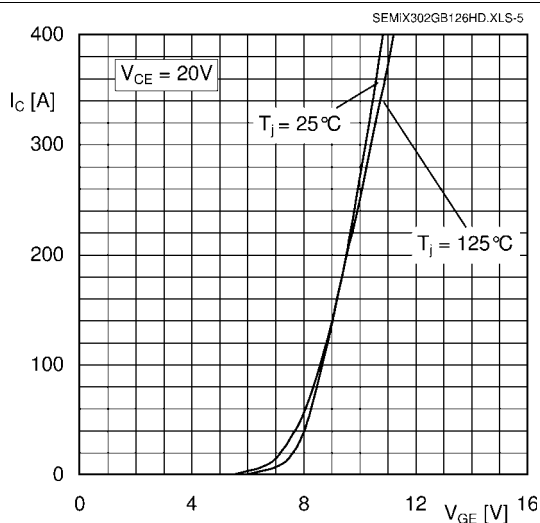


Fig. 5: Typ. transfer characteristic

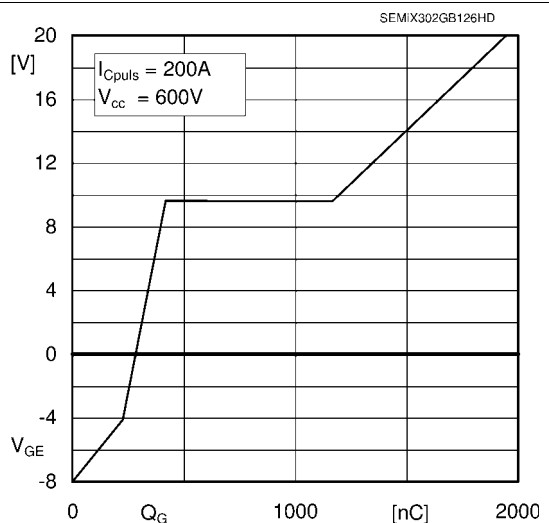


Fig. 6: Typ. gate charge characteristic

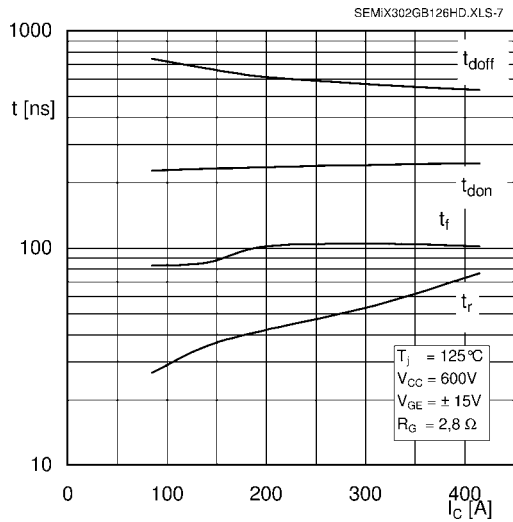


Fig. 7: Typ. switching times vs.  $I_C$

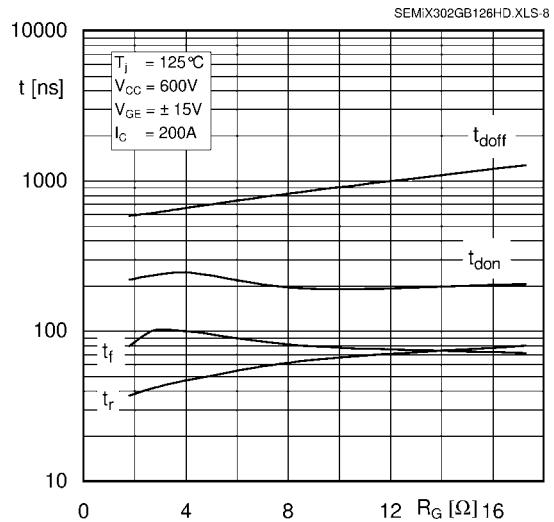


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

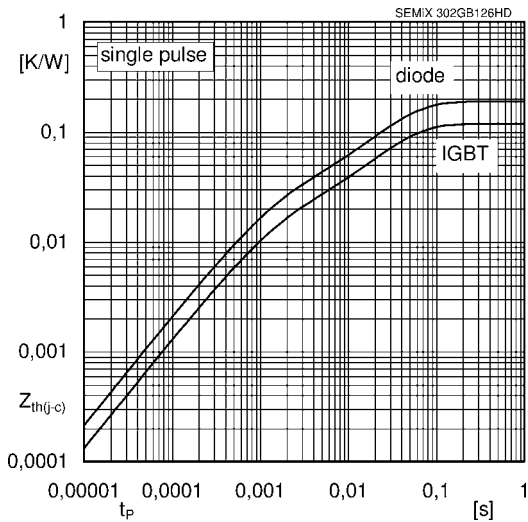


Fig. 9: Typ. transient thermal impedance

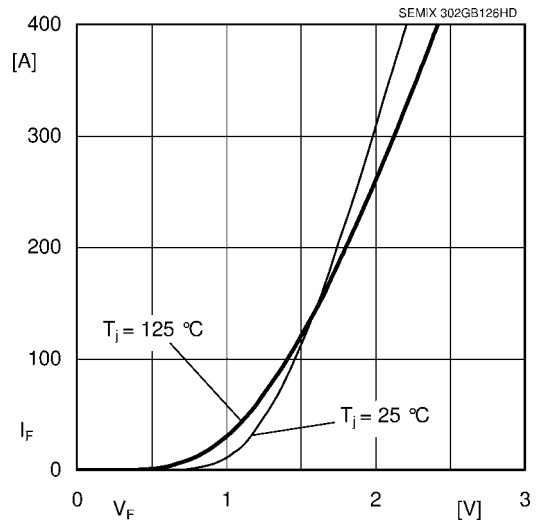


Fig. 10: Typ. CAL diode forward charact., incl.  $R_{CC+EE'}$

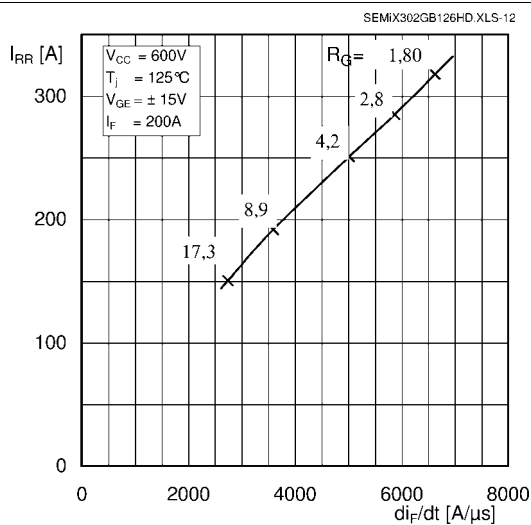


Fig. 11: Typ. CAL diode peak reverse recovery current

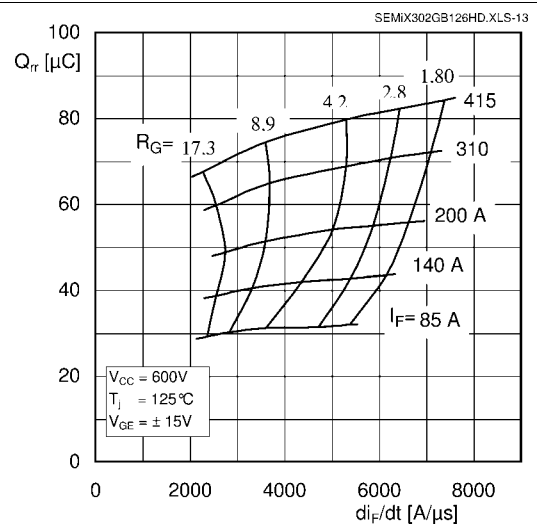


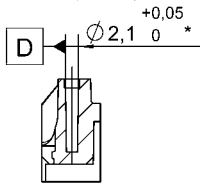
Fig. 12: Typ. CAL diode recovery charge

# SEMiX302GB126HDs

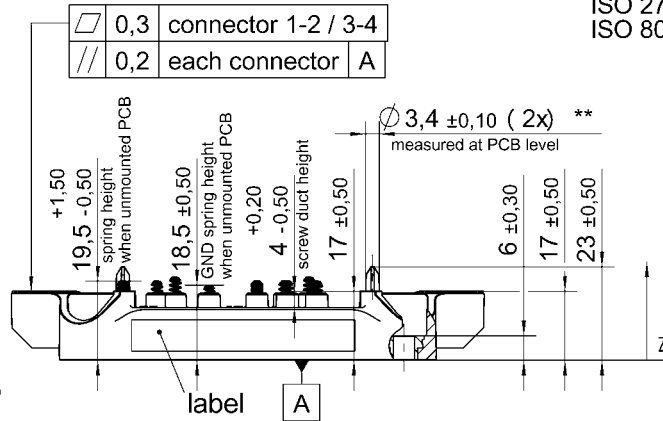
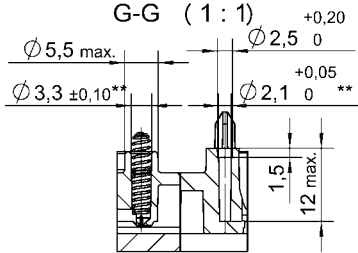
Case: SEMiX 2s

general tolerance:  
ISO 2768-mK  
ISO 8015

screw duct  
(left top) :  
F-F (1:1)

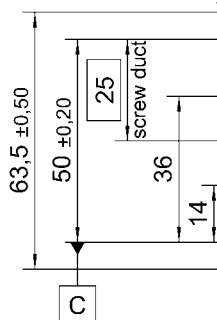


screw duct (4x)  
spring duct (12x) :  
G-G (1:1)

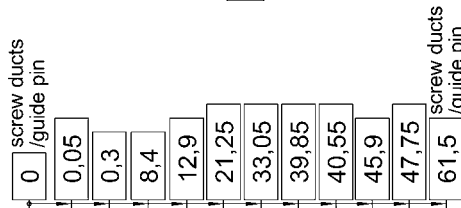
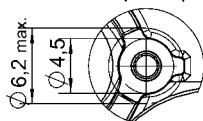


All measures in Z-direction  
valid when mounted to heat sink

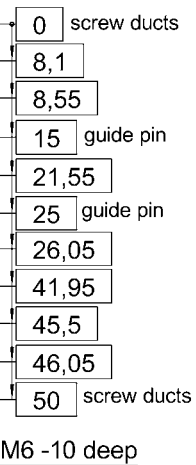
marking of  
terminals



screw duct  
top view (4x) :  
J (2:1)



marking of  
terminals



\*screw duct left / top with



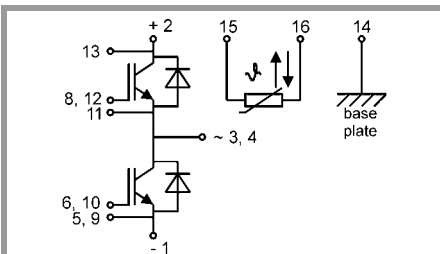
\*\*screw ducts / guide pins / spring ducts with



Rules for the contact PCB:

- holes guidepins =  $\varnothing 4 \pm 0,1$  / position tolerance  $\pm 0,1$
- holes for screws =  $\varnothing 2,9 \pm 0,1$  / position tolerance  $\pm 0,1$
- spring contact pad =  $\varnothing 3,6 \pm 0,1$  / position tolerance  $\pm 0,1$

SEMiX 2s



spring configuration

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.